

Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ Construction utilizes void-free molded plastic technique
- ◆ Low reverse leakage
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed 260°C/10 seconds at terminals

Mechanical Data

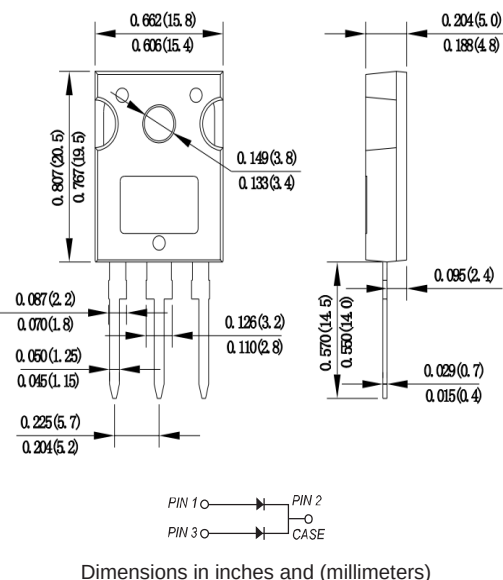
Case : Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750,Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

TO-247



Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	MUR 3005PT	MUR 3010PT	MUR 3020PT	MUR 3040PT	MUR 3050PT	MUR 3060PT	UNITS
Maximum repetitive peak reverse voltage	V _{RRM}	50	100	200	400	500	600	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	350	420	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	500	600	V
Maximum average forward rectified current at T _c =110°C per device per diode	I _(AV)	30.0 15.0						A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I _{FSM}	200.0						A
Maximum instantaneous forward voltage per diode at 15.0A	V _F	1.0			1.3	1.7		V
Maximum DC reverse current at rated DC blocking voltage T _A =25°C T _A =125°C	I _R	10 500						u A
Maximum reverse recovery time	T _{rr}	35						ns
Typical thermal resistance	R _{qJC}	3.5						°C/W
Operating junction temperature range	T _J	-55 to +150						°C
Storage temperature range	T _{STG}	-55 to +150						°C

Note: 1.Reverse recovery time test condition: $I_F=0.5\text{A}$ $I_R=1.0\text{A}$ $I_{rr}=0.25\text{A}$

Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

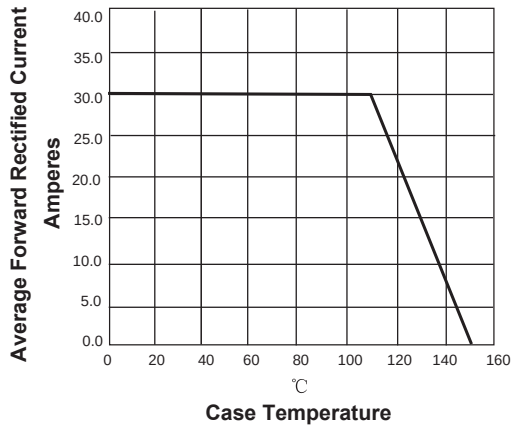


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

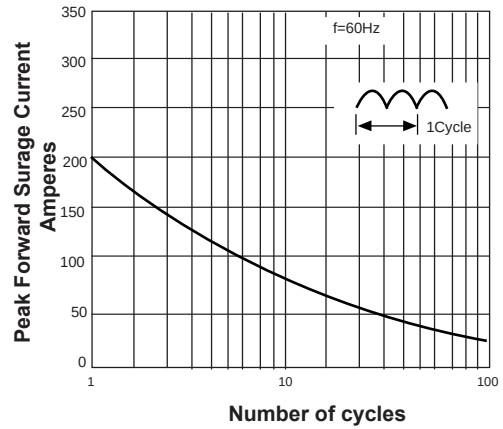


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

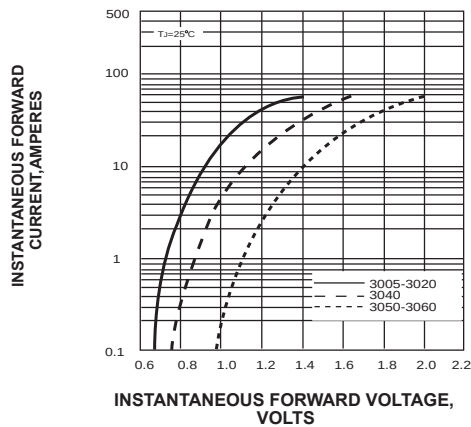
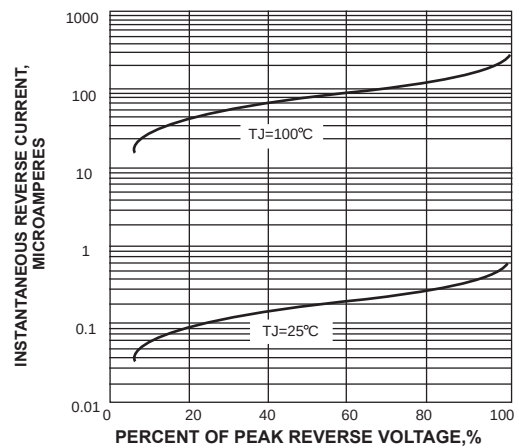
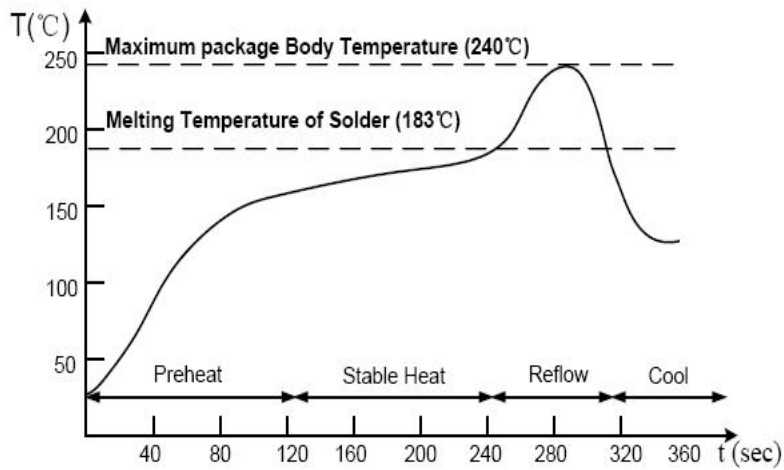


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS



Suggested Soldering Temperature Profile



Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 265°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.